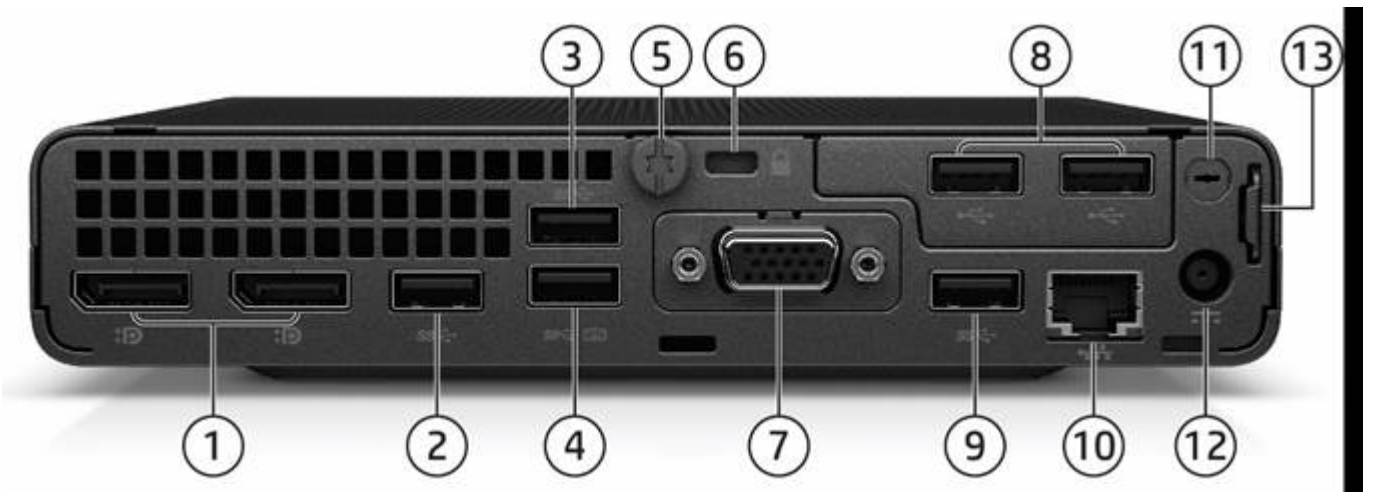
Overview

HP EliteDesk 800 G6 Desktop Mini Business PC

1. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-A SuperSpeed USB 10Gbps signaling rate port
3. Type-A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/2.1A)
4. Combo Audio Jack with CTIA and OMTP headset support
5. Dual-state power button
6. Hard drive activity light

HP EliteDesk 800 G6 Desktop Mini Business PC



1. (2) Dual-Mode DisplayPort™ 1.4 (DP++)
2. Type-A SuperSpeed USB 5Gbps signaling rate port
3. Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
4. Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) Cover release thumbscrew
5. Cover release thumbscrew
6. Standard cable lock slot (10 mm)
8. (1) Flex Port 2, choice of:
   - VR Ready NVIDIA GTX 1660 Ti discrete GPU
   - Dual Type-A Hi-Speed USB 480Mbps signaling rate port
   - SerialS-232
9. Type-A SuperSpeed USB 10Gbps signaling rate port
10. RJ45 network connector
11. External WLAN antenna opening
12. Power connector
13. Retractable Padlock loop

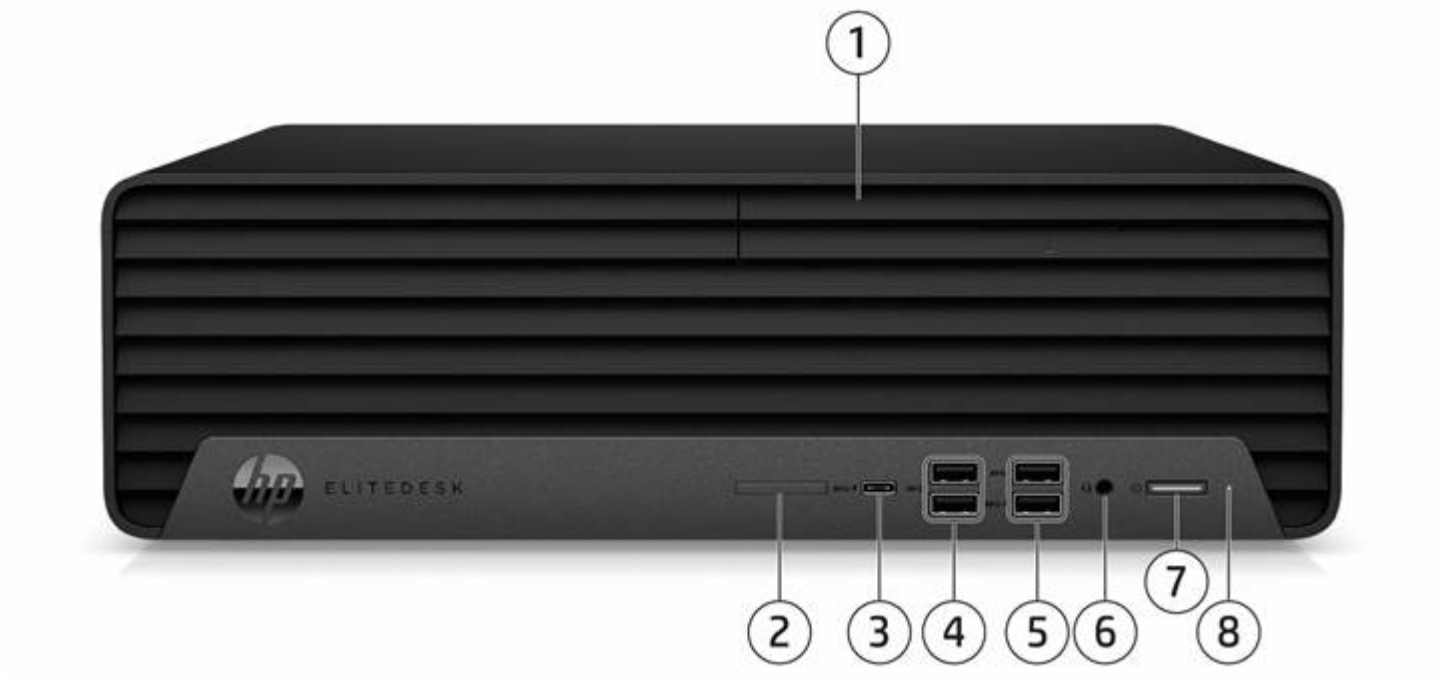
Overview

7. (1) Flex Port 1, choice of:
   - Thunderbolt 3
   - DisplayPort™
   - VGA 2.0a
   - Fiber NIC (100Mbps and 1Gbps)
   - HDMI
   - Type-C™ SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and 100W Power Intake
   - Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)
   - Dual Type A SuperSpeed USB 10Gbps signaling rate port

Not Shown

Slots	(1) Internal M.2 2230 connector for WLAN (2) Internal M.2 SSD storage 2242 and 2280 connector
Bays	(1) 2.5- inch SATA drive Bay (not available on 95W processor)
Mounting	Support for - VESA Sleeve Standalone - Quick Release Bracket - B300/B500 Mounting bracket - Integrated Work Center Stand

HP EliteDesk 800 G6 Small Form Factor Business PC

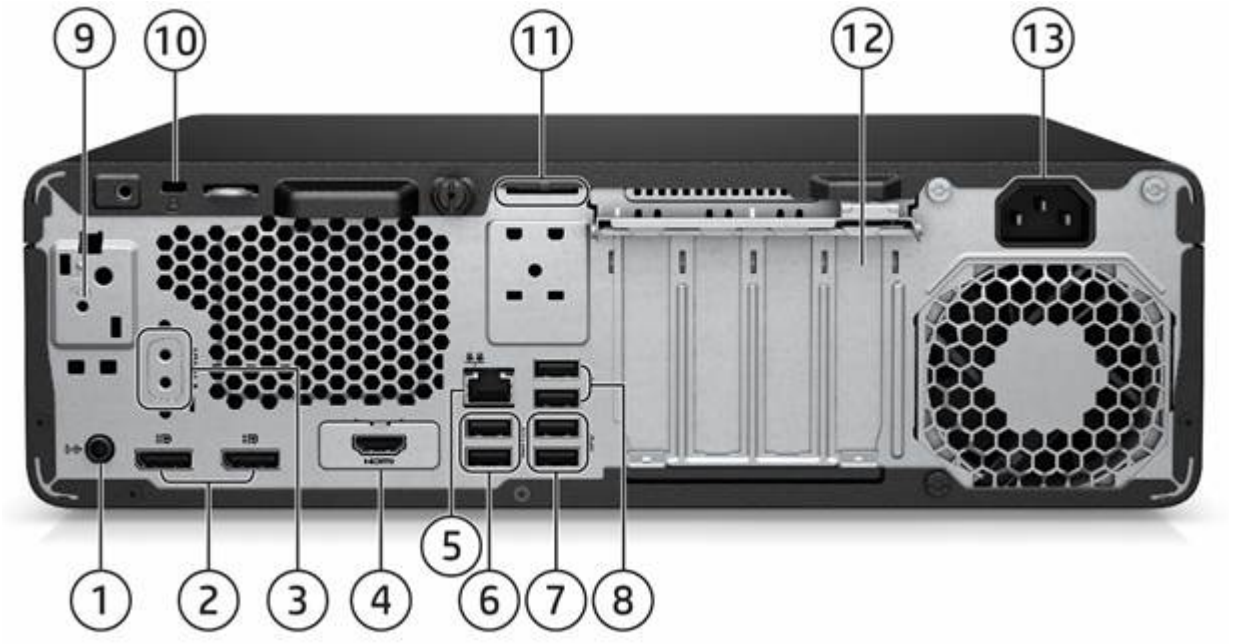


1. Optional Slim optical drive
2. Optional SD 4 Card Reader
3. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support
   up to 5V/3A)
4. Type A SuperSpeed USB 10Gbps signaling rate port (2)
5. Type A SuperSpeed USB 5Gbps signaling rate port (2) (1 with charge support up to 5V/1.5A)
6. Combo Audio Jack with CTIA and OMTP headset support
7. Dual-state power button
8. Hard drive activity light

Overview

HP EliteDesk 800 G6 Small Form Factor Business PC

(Rear Image)



1. Audio line-out connector
2. Dual-Mode DisplayPort™ 1.4a (DP++) (2)
3. Optional Serial port (shown here not installed)
4. Optional port, choice of (shown here HDMI installed):
   - DisplayPort™
   - HDMI 2.0a
   - VGA
   - • Dual Type A SuperSpeed USB 10Gbps signaling rate port
   - USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
5. RJ45 network connector
6. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
7. Type A SuperSpeed USB 10Gbps signaling rate port (2)
8. Type A SuperSpeed USB 5Gbps signaling rate port (2)
9. Optional Internal WLAN antenna cover (shown here not installed)
10. Standard cable lock slot
11. Optional intrusion sensor/hood lock (shown here not installed)
12. Optional Thunderbolt PCIe card with USB-C® (shown here

    not installed)
13. Power cord connector

Not shown

Slots

(2) PCI Express x16 graphics connectors; one wired as an x4
(2) PCI Express x1
(2) internal M.2 SSD storage (2242 and 2280 connector)
(1) internal M.2 WLAN (2230 connector)

Bays

(1) 2.5" internal storage drive bay
(2) 3.5"? internal storage drive bay (convertible to 2.5"?)
(1) 9.5 mm slim optical drive bay

Overview

HP EliteDesk 800 G6 Tower Business PC

1. Optional Slim optical drive
2. External 5.25-inch Half-Height Drive Bay (behind bezel)
3. Hard drive activity light
4. Dual-state power button
5. Combo Audio Jack with CTIA and OMTP headset support
6. Type A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/1.5A) (2)
7. Type-A SuperSpeed USB 10Gbps signaling rate port (2)
8. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
9. Optional SD card 4.0 reader

Overview

HP EliteDesk 800 G6 Tower Business PC

5.5

1. Audio line-out jack for powered audio devices
2. Dual-Mode DisplayPort™ 1.4 (DP++) (2)
3. Optional port, choice of (shown here HDMI installed):
   - DisplayPort™ 1.4
   - HDMI 2.0a
   - VGA
   - Dual Type A SuperSpeed USB 10Gbps signaling rate port
   - USB-C® SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
4. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
5. Type A SuperSpeed USB 10Gbps signaling rate port (2)
6. Type A SuperSpeed USB 5Gbps signaling rate port (2)
7. Optional Internal WLAN antenna cover (shown here installed)
8. Standard cable lock slot
9. RJ-45 (network) jack
10. Optional intrusion sensor/hood lock (shown here not installed)
11. Optional serial port (shown here not installed)
12. Optional Thunderbolt PCIe card with USB-C® (shown here not installed)
13. Power cord connector

Not shown

Slots

(2) PCI Express x16 graphics connectors; one wired as an x4
(2) PCI Express x1
(2) internal M.2 SSD storage (2242 and 2280 connector)
(1) internal M.2 WLAN (2230 connector)

Bays

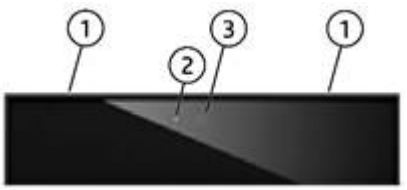
(1) 2.5" internal storage drive bay
(2) 3.5"? internal storage drive bay (convertible to 2.5"?)
(1) 5.25"? half-height drive bay
(1) 9.5mm slim optical drive bay

Overview

HP EliteOne 800 G6 24 & 27 All-in-One*

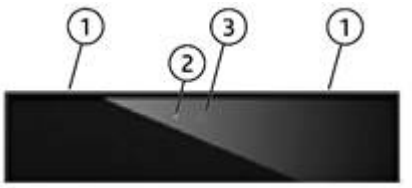
1. Camera (optional)
2. Speakers (optional)

HD Webcam (optional)



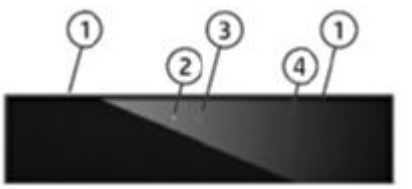
1. Dual Microphones
2. Webcam Light
3. HD Webcam

5MP Webcam (optional)



1. Dual Microphones
2. Webcam Light
3. 5MP Webcam

5MP Webcam with Infrared (IR) Sensors (optional)



1. Dual Microphones
2. Webcam Light
3. IR/5MP Webcam
4. IR Light

*Available Options: Touch, Non-Touch, HP Sure View (24"? Display Only), and Discrete Graphics

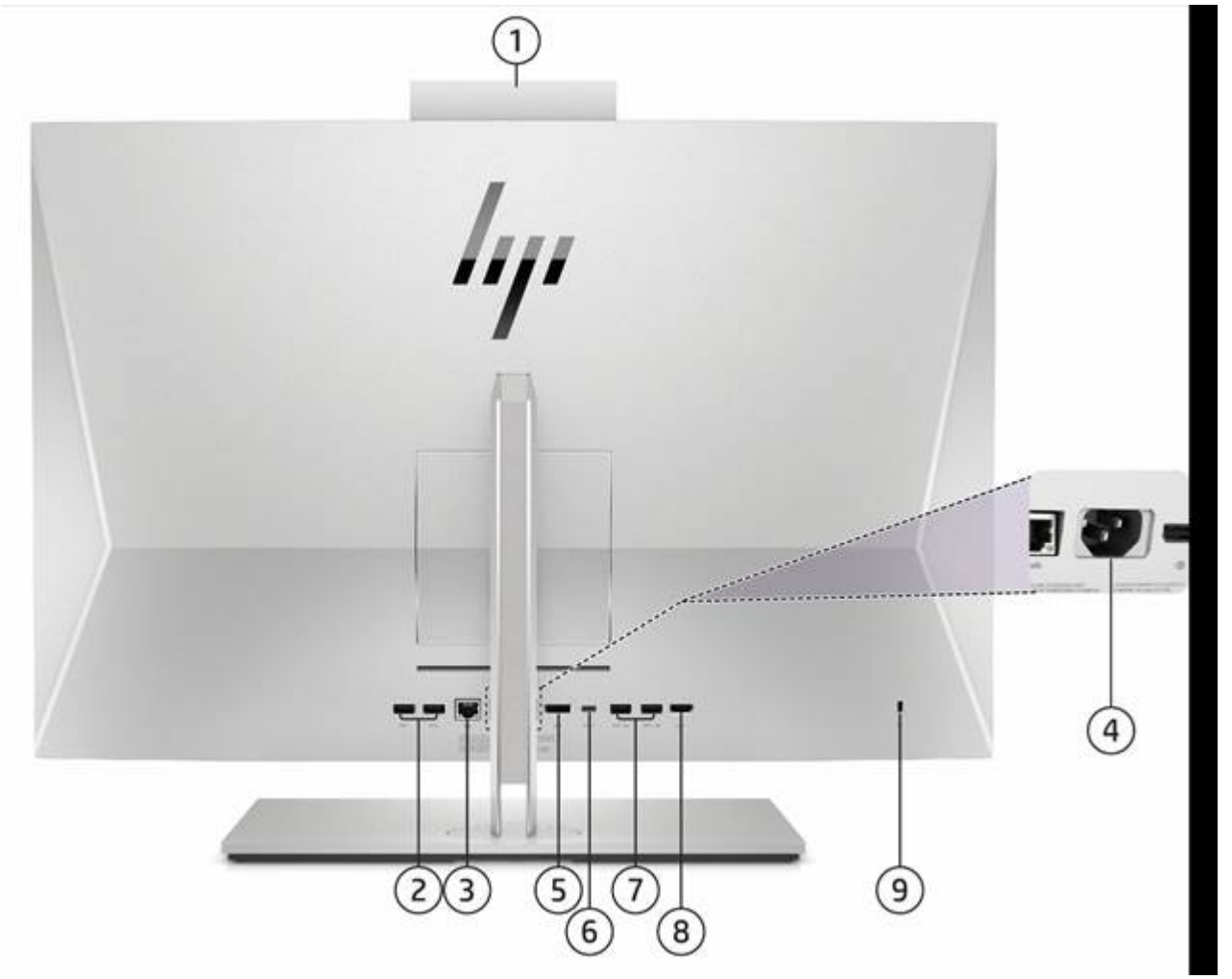
Overview

HP EliteOne 800 G6 24 & 27 All-in-One*

1. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
2. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
3. Combo Audio Jack with CTIA and OMTP headset Support

Overview

HP EliteOne 800 G6 24 & 27 All-in-One

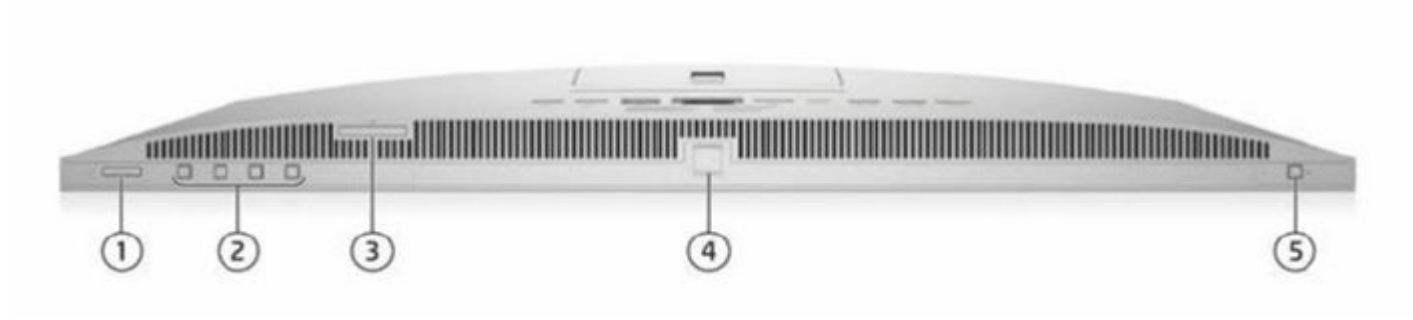


Rear components and rear ports

1. Camera (optional)
2. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
3. RJ-45 network connector/jack USB 3.1 Gen 2 Type-A port (charge support up to 5V/1.5A)
4. Power Connector
5. Dual-Mode DisplayPort™1.4 (DP++)
6. Type-C® SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
7. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
8. HDMI-in 2.0a connector
9. Standard cable lock slot

Overview

HP EliteOne 800 G6 24 & 27 All-in-One



Bottom

1. Dual-State Power button
2. OSD control buttons
3. SD card reader 4.0 (optional)
4. Fingerprint Sensor (optional)
5. HP Sure View Button (optional on 23.8"? only)

Not shown

Slots

(1) internal M.2 PCIe x1 connector for optional wireless NIC
(2) internal M.2 PCIe x4 connector for optional m.2 SSD

VESA

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)

Features

At A Glance

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- Intel® Q470 chipset supporting Intel® 10th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro™ Technology (available with Core i3, Core i5, Core i7 and Core i9 processors) [1,4]
- Processors up to 65W on AiO
- Processors up to 95W on DM
- Processors up to 125W on DM, TWR and SFF
- Intel® Optane™ Memory H10 with Solid State Storage
- Intel® UHD graphics with optional discrete graphics configure systems to up to 7 monitors (TWR, SFF and DM 35W)
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6 + BT5 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2933 MT/s)[2]
- Support for up to 7 monitors via two standard DisplayPort™ 1.4 ports,a configurable Flex i/o port for video options and a discr graphics card on TWRs, SFFs and DMs. AiO supports up to two additional monitors via DisplayPort™ or Type-C® USB in alternat mode.
- Configurable FlexPort which provides the following choices: HDMI 2.0, Serial, VGA, DisplayPort™ 1.4, or USB Type-C™ with DisplayPort™ 1.4 (USB Type-C® with DisplayPort™ 1.4 with Power Delivery {PD] on DMs), Thunderbolt 3.0 (port on DM, PCIe ca on TWR, SFF) and Dual USB Type-A for (TWRs, SFFs and DMs). See Ports section for port availability by platform. FlexPort not supported on AIO.
- 2nd FlexPort available for configuration on the HP EliteDesk G6 Desktop Minis with the following ports: Serial, and Dual USB Type A. FlexPort not supported on AIO.
- Configurable NVIDA® GeForce®VR ready discrete graphics card with (3) mini-DisplayPorts and (1) micro-HDMI video port for DM to support up (7) monitors with minimum 4K resolution and option to connect up to (3) monitors with 5K resolution via grap card.
- Configurable AMD® Radeon and NVIDA® GeForce® VR ready discrete graphics on AiO.[5]
- Configurable AMD® Radeon, NVIDA® GeForce® and NVIDA® Quadro® VR ready discrete graphics on TWR [5]
- Compatibility with HP Mini-In-One 24 Display (800 G6 DM with 100W USB-C +PD option card)
- Compatible with HP Reverb VR Headset (AiO, TWR and DM)
- Models can be configured with multiple data drives in a RAID array
- Zoom Rooms edition available (AiO, DM) with Win IoT
- Audio by Bang & Olufsen (AiO)
- Intel® Unite™ available (AiO, DM)[6]
- Integrated Low Blue Light Panels on AiO (excludes Sure View and Touch Models)
- Enhanced Security whit HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.
- CCC, CECP and SEPA Certified (TWR/SFF/DM/AiO)
- TCO Edge for AiO (TCO Edge not available for models with HP Sure View)
- TCO (TWR/SFF/DM)
- PC chassis and all internal components and modules are manufactured with low halogen content [3]
- Dust filter available for following platforms (35W DM, SFFs and TWRs)
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Maximum transfer rate only available with Intel® Core i7 and Core i9 Processors.
3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined.

Features

5. VR-ready as optional feature, requires specific configuration to support.
6. Intel® Unite™ must be configured at the factory.

NOTE: See important legal disclosures for all listed specs in their respective feature´s sections

PRODUCT NAME

HP EliteDesk 800 G6 Tower PC
HP EliteDesk 800 G6 Small Form Factor PC
HP EliteDesk 800 G6 Desktop Mini PC
HP EliteOne 800 G6 24 All-in-One PC
HP EliteOne 800 G6 27 All-in-One PC

OPERATING SYSTEM

Preinstalled	Windows® 10 Pro 64[1] Windows® 10 Pro 64 (National Academic License)[2] Windows® 10 Home 64[1] Windows® 10 Home 64 Single Language[1] FreeDOS
Web-supported only	Windows® 10 Enterprise 64[1]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

SUPPORTED VERSIONS

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

CHIPSET

	DM	SFF	TWR	AiO
Intel® Q470 PCH-H- vPro™	X	X	X	X

PROCESSORS

Intel® 10th Generation Core™ Processors	DM	SFF	TWR	AiO
Intel® Core™ i9 10900K Processor with Intel® UHD Graphics 630 (3.7GHz, up to 5.2 GHz with Intel® Turbo Boost,20MB cache, 10 cores) 125W[1,2,4] Supports Intel® vPro™ Technology[3]	X	X	X	

Features

Intel® Core™ i10900 Processor with Intel® UHD Graphics 630 (2.8GHz, up to 5.1 GHz with Intel® Turbo Boost,20MB cache, 10 cores) 65W[1,2] Supports Intel® vPro™ Technology[3]	X	X	X	X
Intel® Core™ i9 10900T Processor with Intel® UHD Graphics 630 (1.9GHz, up to 4.6 GHz with Intel® Turbo Boost,20MB cache, 10cores) 35W[1,2] Supports Intel® vPro™ Technology[3]	X			
Intel® Core™ i7 10700K Processor with Intel® UHD Graphics 630 (3.8 GHz, up to 5.1 GHz with Intel® Turbo Boost,16MB cache, 8 cores) 125W[1,2,4] Supports Intel® vPro™ Technology[3]	X	X	X	
Intel® Core™ i7 10700 processor with Intel® UHD Graphics 630 (2.9 GHz, up to 4.8 GHz with Intel® Turbo Boost, 16 MB cache, 8 cores) 65W[1,2] Supports Intel® vPro™ Technology[3]	X	X	X	X
Intel® Core™ i7 10700T Processor with Intel® UHD Graphics 630 (2.0 GHz, up to 4.4 GHz with Intel® Turbo Boost,16MB cache, 8 cores) 35W[1,2] Supports Intel® vPro™ Technology[3]	X			
Intel® Core™ i5 10600K processor with Intel® UHD Graphics 630 (4.1 up to 4.8 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) 125W [1, 2,4] Supports Intel® vPro™ Technology[3]	X	X	X	
Intel® Core™ i5 10600 processor with Intel® UHD Graphics 630 (3.3 GHz, 12 MB cache, 6 cores) 65W[1, 2] Supports Intel® vPro™ Technology[3]	X	X	X	X
Intel® Core™ i5 10600T processor with Intel® UHD Graphics 630 (2.4 GHz 12 MB cache, 6 cores) 35W[1, 2] Supports Intel® vPro™ Technology[3]	X			
Intel® Core™ i5 10500 processor with Intel® UHD Graphics 630 (3.1 GHz, 12 MB cache, 6 cores) 65W[1, 2] Supports Intel® vPro™ Technology[3]	X	X	X	X
Intel® Core™ i5 10500T processor with Intel® UHD Graphics 630 (2.3 GHz, 12 MB cache, 6 cores) 35W[1, 2] Supports Intel® vPro™ Technology[3]	X			
Intel® Core™ i5 10400 processor with Intel® UHD Graphics 630 (2.9 GHz, 12 MB cache, 6 cores) 65W[1, 2]	X	X	X	X
Intel® Core™ i5 10400T processor with Intel® UHD Graphics 630 (2.0 GHz, 12 MB cache, 6 cores) 35W [1, 2]	X			
Intel® Core™ i3 10320 processor with Intel® UHD Graphics 630 (3.8 GHz, 8 MB cache, 4 cores) 65W[1]	X	X	X	X
Intel® Core™ i3 10300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores) 65W[1]	X	X	X	X
Intel® Core™ i3 10300T processor with Intel® UHD Graphics 630 (3.0 GHz, 8 MB cache, 4 cores) 35W[1]	X			
Intel® Core™ i3 10100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores) 65W[1]	X	X	X	X
Intel® Core™ i3 10100T processor with Intel® UHD Graphics 630 (3.0 GHz, 6 MB cache, 4 cores) 35W[1]	X			

Features

Intel® Pentium® Processors	DM	SFF	TWR	AiO
Intel® Pentium® Gold G6600 processor with Intel® UHD Graphics 630 (4.2 GHz, 4 MB cache, 2 cores) 65W[1]	X	X	X	X
Intel® Pentium® Gold G6500 processor with Intel® UHD Graphics 630 (4.1 GHz, 4 MB cache, 2 cores) 65W[1]	X	X	X	X
Intel® Pentium® Gold G6500T processor with Intel® UHD Graphics 630 (3.5GHz, 4 MB cache, 2 cores) 35W[1]	X			
Intel® Pentium® Gold G6400 processor with Intel® UHD Graphics 610 (4.0 GHz, 4 MB cache, 2 cores) 65W[1]	X	X	X	X
Intel® Pentium® Gold G6400T processor with Intel® UHD Graphics 610 (3.4 GHz, 4 MB cache, 2 cores) 35W[1]	X			

GRAPHICS

Integrated Intel® Graphics	DM	SFF	TWR	AiO
Intel® UHD Graphics 630 (integrated on 10th gen Core i9/i7/i5/i3, Pentium® Gold G6600, G6500)	X	X	X	X
Intel® UHD Graphics 610 (integrated on 10th gen Pentium® Gold G6400, Celeron® G5900, G5920)	X	X	X	X

Optional Discrete Graphics Solutions	DM	SFF	TWR	AiO
NVIDIA® GeForce® RTX 2080 Super 8GB FH 3DP HDMI Graphics Card*			X	
NVIDIA® GeForce® RTX 2070 Super 8GB FH 3DP HDMI Graphics Card				X
NVIDIA® GeForce® RTX 2060 Super 8GB FH DP HDMI DVI-D Graphics Card*			X	
NVIDIA® Quadro P2200 5GB 4DP Graphics Card			X	
NVIDIA® Quadro P1000 4GB 4mDP Graphics Card			X	
NVIDIA® Quadro P620 2GB Graphics Card		X	X	
NVIDIA® Quadro P400 2GB Graphics Card		X	X	
NVIDIA® GeForce® GTX 1660Ti 6GB HMDI, DP Graphics Card**	X			
AMD® Radeon™ RX 5300 3GB NGC Graphics Card				X
AMD® Radeon™ RX 550X 4GB DP HDMI Graphics Card		X	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit DP+VGA***		X	X	
AMD® Radeon™ R7 430 2GB GDDR5 64bit 2DP		X	X	

*Requires 550W chassis
** Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro -HDMI 2.0 port in order to drive up to 7 displays directly on the Desktop Mini.
***Not available in all regions
NOTE: The TWR can support a single discrete graphics card up to 300W with a 550W Power Supply.

Features

Adapters and Cables	DM	SFF	TWR	AiO
HP DisplayPort™ Cable	X	X	X	X
HP DisplayPort™ to DVI-D Adapter	X	X	X	X
HP DisplayPort™ to HDMI True 4K Adapter	X	X	X	X
HP DisplayPort™ to VGA Adapter	X	X	X	X
HP USB to Serial Port Adapter	X	X	X	X
HP USB-C® to HDMI 4K Adapter	X	X	X	X
HP USB-C® to DisplayPort Adapter	X	X	X	X
HP DVI Cable	X			X
HP HDMI Standard Cable Kit (HDMI)		X	X	X
HP DVI Cable Kit	X			X
Micro HDMI to HDMI Adapter	X	X	X	
Mini DisplayPort to DisplayPort Adapter	X			

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	DM	SFF	TWR	AiO
500GB 7200RPM 3.5in SATA HDD		X	X	
1TB 7200RPM 3.5in SATA HDD		X	X	
2TB 7200RPM 3.5in SATA HDD		X	X	

2.5 inch SATA Hard Disk Drives (HDD)	DM	SFF	TWR	AiO
500GB 7200RPM 2.5in SATA HDD	X	X	X	
1TB 7200RPM 2.5in SATA HDD	X	X	X	
2TB 5400RPM 2.5in SATA HDD	X	X	X	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	X	X	X	
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	X	X	X	

* Storage DriveLock does not work with Self Encrypting or Optane based storage

M.2 PCIe NMVe Solid State Drives (SSD)	DM	SFF	TWR	AiO
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	X	X	X	X
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
256GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X

Features

512GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X

* Storage DriveLock does not work with Self Encrypting or Optane based storage

Optical Disc Drives	DM	SFF	TWR	AiO
HP 9.5mm Slim DVD-ROM Drive		X	X	
HP 9.5mm Slim DVD Writer Drive		X	X	
HP 9.5mm Slim Blu-Ray Writer Drive		X	X	

Media Card Reader	DM	SFF	TWR	AiO
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		X	X	X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

MEMORY

Memory Type	DM	SFF	TWR	AiO
DDR4-2933 (Transfer rates up to 2933 MT/s), 64 GB, 2 SODIMM[1]	X			X
DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 2 SODIMM	X			X
DDR4-2933 (Transfer rates up to 2933 MT/s), 128 GB, 4 DIMM[1]		X	X	
DDR4-2666 (Transfer rates up to 2666 MT/s), 128 GB, 4 DIMM		X	X	

Memory Configuration	DM	SFF	TWR	AiO
4 GB (1 x 4 GB)	X	X	X	X
8 GB (2 x 4 GB)	X	X	X	X
8 GB (1 x 8 GB)	X	X	X	X
16 GB (2 x 8 GB)	X	X	X	X
16 GB (1 x 16 GB)	X	X	X	X
32 GB (2 x 16 GB)	X	X	X	X
32 GB (4 x 8 GB)		X	X	
32 GB (1 x 32 GB)	X	X	X	X
64 GB (4 x 16 GB)		X	X	
64 GB (2 x 32 GB)	X	X	X	X
128 GB (4 x 32 GB)		X	X	

1. Only available with Intel Core i7 and Core i9 processors.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

Memory modules support data transfer rates up to 2666 MT/s or 2933 MT/s as depending on processor config; with 1 DIMM per channel. Additional DIMM loading on any channel may impact maximum memory speed. Actual data rate is determined by the system's configured ; See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Features

Ethernet (RJ-45)	DM	SFF	TWR	AiO
Intel® I225LM 2.5 Gigabit Network Connection LOM (optional)	X			
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		X	X	
Intel® I219-LM Gigabit Network Connection LOM (standard)	X	X	X	X

Wireless[1]	DM	SFF	TWR	AiO
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 vPro, supporting gigabit file transfer speed)	X	X	X	X
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit file transfer speed)	X	X	X	X
Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + BT5	X	X	X	X

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

KEYBOARDS AND POINTING DEVICES

Keyboards	DM	SFF	TWR	AiO
HP Wired Desktop 320K Keyboard	X	X	X	X
HP USB Premium Keyboard	X	X	X	X
HP USB and PS/2 Washable Keyboard[1]	X	X	X	X
HP USB Business Slim Smart Card (CCID) Keyboard	X	X	X	X
HP USB Keyboard	X	X	X	X
HP PS/2 Business Slim Keyboard[1]		X	X	
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X
HP USB Business Slim Antimicrobial Keyboard[2]	X	X	X	X
HP Wireless Premium Keyboard and Mouse	X	X	X	X
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X

Mouse	DM	SFF	TWR	AiO
HP Wired Desktop 320M Mouse	X	X	X	X
HP PS/2 Mouse[1]		X	X	
HP USB Optical Mouse	X	X	X	X
HP USB Premium Mouse	X	X	X	X
HP USB 1000dpi Laser Mouse	X	X	X	X
HP USB and PS/2 Washable Mouse[1]	X	X	X	
Antimicrobial USB Mouse[2]	X	X	X	X
HP USB Hardened Mouse[2]	X	X	X	X
HP USB Fingerprint Reader Mouse	X	X	X	X

1. PS/2 port not available on EliteOne 800 G6 AiOs and not available on any EliteDesk 800 G6 DMs
2. Not available in all regions

Features

SECURITY

	DM	SFF	TWR	AiO
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	X	X	X	X
Solenoid Lock & Intrusion Sensor		X	X	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			X
Support for chassis cable lock devices	X (10 mm or smaller)	X	X	X
Support for chassis padlocks devices	X	X	X	
HP Fingerprint Sensor (standard on 800 G6 AiO touch models and optional on non-touch models)				X
SATA port disablement (via BIOS)	X	X	X	
Serial, USB enable/disable (via BIOS)	X	X	X	X
Intel® Identify Protection Technology (IPT)[1]	X	X	X	X
Serial, parallel, USB enable/disable (via BIOS)	X	X	X	X
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	X	X
Removable media write/boot control	X	X	X	X
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	X	X	X	X

1. Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.

PORTS

I/O Ports - Internal Ports	DM	SFF	TWR	AiO
Internal SATA storage connector(s)	N/A	3	4	N/A
Internal SATA storage connector (Data and Power)	1	N/A	N/A	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Features

Standard User Accessible Ports	DM	SFF	TWR	AiO
Type-A Hi-Speed USB		2 (rear)	2 (rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port	1 (front) 2 (rear)	2 front (1 fast charging), 2 rear	2 front (1 fast charging), 2 rear	2 rear
Type-A SuperSpeed USB 10 Gbps signaling rate port	1 (front) 2 (rear)	2 front; 2 rear	2 front; 2 rear	2 rear 1 side
Type-C® SuperSpeed USB 10 signaling rate Gbps port	1 (front)	1 (front)	1 (front)	1 rear 1 side
Video	2 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.4 (rear)	1 DisplayPort™ 1.4 (rear)	For models with integrated graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and OMTP headset support (front)	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 CTIA/OMTP UAJ (side)
Network Interface	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)

(1) Flexible Port 1, choice of one of the following"?	DM	SFF	TWR	AiO
Type-A SuperSpeed USB 5 Gbps signaling rate port	2 (rear)	2 (rear)	2 (rear)	N/A
Type-C® SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)*	N/A
Thunderbolt™ 3	1 (rear)	1 (rear)	1 (rear)	N/A
Video	1 DisplayPort™ 1.4 or HDMI 2.0 or VGA (rear)	1 DisplayPort™ 1.4 or HDMI 2.0 or VGA (rear)	1 DisplayPort™ 1.4 or HDMI 2.0 or VGA (rear)	N/A
Serial (RS-232)	N/A	1 (rear)	1 (rear)	N/A
Fiber NIC Adapter	(1) 100Mbps NIC (rear) (1) 1 Gbps NIC (rear)			N/A
RJ-45 Ethernet NIC	(1) 2.5GbE(rear)			N/A

Features

(1) Flexible Port 2, choice of one of the following:	DM	SFF	MT	AiO
Type-A USB	2 Hi-Speed USB (rear)			N/A
Serial (RS-232)	1 (rear)			N/A
Discrete Graphics	1 (rear)			N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Slots	DM	SFF	TWR	AiO
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280 Combo (for storage)
PCI Express v3.0 x1	N/A	2	2	N/A
PCI Express v3.0 x16 (wired as x4)	N/A	1	1	N/A
PCI Express v3.0 x16	N/A	1 (up to 75W)	1 (up to 300W)	N/A

Bays	DM	SFF	TWR	AiO
5.25" Half Height (External)	N/A	N/A	1	N/A
9mm Slim Optical Disc Drive (ODD)	N/A	1	1	N/A
SD Card Reader	N/A	1	1	1
2.5" Internal Storage Drive	1	1	1	N/A
3.5" Internal Storage Drive	N/A	2	2	N/A

SATA 2.5"? internal storage drive cannot be selected if 2nd M.2, discrete graphic card, or 95W processor is selected.

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS
HP BIOSphere Gen6 [16]
HP DriveLock & Automatic DriveLock[20]
BIOS Update via Network
HP Secure Erase [18]
Absolute Persistence Module [19]
Pre-boot Authentication

Features

HP Wake on WLAN

Software
HP Desktop Support Utility
HP JumpStart
HP Privacy Settings
HP Setup Integrated OOBE
HP Support Assistant [21]
HP Noise Cancellation Software
Buy Office (sold separately)

Manageability Features
HP Driver Packs [22]
HP System Software Manager (SSM) (download)
HP BIOS Config Utility (BCU) (download)
HP Client Catalog (download)
HP Image Assistant Gen (download)
HP Manageability Integration Kit for Microsoft System Center Configuration Management Gen4 [23]
Ivanti Management Suite (download)[24]
HP Cloud Recovery[39]
HP Client Management Script Library (download)

Client Security Software
HP Client Security Suite Gen6[25]
HP Power On Authentication
Windows Defender[27]

Security Management
Trusted Platform Module TPM 2.0 Embedded Security Chip shipped with Windows 10. (Common Criteria EAL4+ Certified).
SATA 0,1 port disablement (via BIOS)
Serial, USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
Support for chassis padlocks and cable lock devices
HP Sure Sense[34]
HP Sure Click[38]
HP Sure Start Gen6[30]
HP Sure Run Gen3[35]
HP Sure Recover Gen3[36]

16. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
18. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
20. Storage Drivelock does not work with Self Encrypting or Optane based storage.
21. HP Support Assistant requires Windows and Internet access.
22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
24. Ivanti Management Suite subscription required.
25. HP Client Security Manager Gen6 requires Windows and is available on select HP Pro and Elite PCs.
27. Windows Defender Opt in Windows 10 and internet connection required for updates.
30. HP Sure Start Gen6 is available on select HP PCs with Intel processors.
34. HP Sure Sense requires Windows 10.
35. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
36. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. Not available on platforms with multiple internal

Features

storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
38. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
39. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.
Low halogen (chassis, all internal components and modules)[1]
TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign mat can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosur and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)[1] Non-operating: -22° to 149° F (-30° to 65° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

HP EliteDesk 800 Desktop Mini G6 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop.

Features

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured - Idle		
Fixed Disk - Random writes		

Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.

Features

	• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. ***NOTE:** Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.		
Packaging Materials	**External:**	PAPER/Corrugated	322 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	33 g
		PLASTIC/Polyethylene low density	5 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently		

Features

	handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is poste on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used b recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 800 Small Form Factor G6 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

Features

	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured - Idle		
Fixed Disk-Random writes		

Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration

Features

	varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. ***NOTE:** Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.		
Packaging Materials	**External:**	PAPER/Corrugated	1158 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	320 g
		PLASTIC/Polyethylene low density	28 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.		
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.		

Features

	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 800 Tower G6 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared			

Features

Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured - Idle			
Fixed Disk-Random writes			
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 35% post-consumer recycled plastic (by wt.); Including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. ***NOTE:** Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.		
Packaging Materials	**External:**	PAPER/Corrugated	1170 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	378 g
		PLASTIC/Polyethylene low density	17 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos		

Features

	• Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteOne 800 G6 23.8-in All-in-One

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018.

Features

System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured - Idle			
Fixed Disk - Random writes			
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: storage, Memory and processor. Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight		

Features

	Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 40% post-consumer recycled plastic (by wt.); including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. ***NOTE:** Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.		
Packaging Materials	**External:**	PAPER/Corrugated	
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	
		PLASTIC/Polyethylene low density	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly.		

Features

	• Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pd and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteOne 800 G6 27 All-in-One PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018.		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the mode family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

Features

	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)
Typically Configured - Idle		
Fixed Disk - Random writes		

Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See www.epeat.net for registration status by country. According to IEEE 1680.1-2018. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains a minimum of 40% post-consumer recycled plastic (by wt.); including 10% ITE-derived post-consumer recycled plastic* • This product is 95.1% recycle-able when properly disposed of at end of life. *NOTE: Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.

Packaging Materials	**External:**	PAPER/Corrugated	322 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	32 g
		PLASTIC/Polyethylene low density	5 g

Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics • Cadmium

Features

	• Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is poste on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used b recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

Features

HP EliteDesk 800 G6 Tower Business PC

On-site Warranty[15]: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day[16] service for parts and labor and includes free support 24 x 7[17]. Three-year onsite and labor are not available in all countries. Service offers terms up to years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[18]

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Small Form Factor Business PC

On-site Warranty[15]: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day[16] service for parts and labor and includes free support 24 x 7[17]. Three-year onsite and labor are not available in all countries. Service offers terms up to years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[18]

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Desktop Mini Business PC

On-site Warranty[15]: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day[16] service for parts an labor and includes free support 24 x 7[17]. Three-year onsite and labor are not available in all countries. Service offers terms up to years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[18]

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Features

HP EliteOne 800 G6 24 & 27 All-in-One Business PC

On-site Warranty[15]: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day[16] service for parts and labor and includes free support 24 x 7[17]. Three-year onsite and labor are not available in all countries. Service offers terms up to years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[18]

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT ® registration varies by country. See http://www.epeat.ne for registration status by country. According to IEEE 1680.1-2018.

PROCESSORS

Intel® 10th Generation Core™ Processors

All HP EliteDesk 800 G6 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G6 Business PC.

Intel® Advanced Management Technology (AMT) v12 - An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework

DISPLAY PANEL SPECIFICATIONS

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points

Non-Touch Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	250nits
Viewing angle (HxV)	178 ° x 178 °
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) with HP Sure View (optional)

Type	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	285 nits (non-Privacy); 400 nits (Privacy)
Viewing angle (HxV)	178° x 178° (non-Privacy); 80° x 178° (Privacy)
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

Technical Specifications – Display Panel Specifications

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	597.888 x 336.312
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.3114 x 0.3114
Contrast ratio	1000:1
Brightness	250nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (2560 x 1440) Touch

Support HW low blue light feature

Type	IPS WLED Backlit LCD
Active area (mm)	596.736 x 335.664
Native Resolution (HxV)	2560 x 1440
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2331 x 0.2331
Contrast ratio	1000:1
Brightness*	300nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

1. All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.
2. For All in One only Intel® HD Graphics (integrated)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot
Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel

GRAPHICS

HP EliteDesk 800 G6 Desktop Mini Business PC

Intel® HD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features Supports HDCP 2.3 Supports audio over HDMI
VGA (optional)	VGA output
USB-C® DP Alt Mode (optional)	DisplayPort over the optional USB-C® module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optima balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

Nvidia® GeFORCE® GTX1660 Ti

Architecture	Discrete GPU Nvidia® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Maximun pixel clock :1.3 GHz pixels per second Maximun bandwidth :25.92 Gbps per connector (FEC Disable)
HDMI	Supports HDMI 2.0 features Supports HDCP 2.2, HDR
Memory	6GByte, 192bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenGL 4.6
Display Port	Support DP1.4(DSC1.2a) Maximum pixel clock :1.3 GHz pixels per second Maximum bandwidth :25.92 Gbps per connector (FEC Disable)
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings
Port Availability	(3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port

HP EliteDesk 800 G6 Tower Business PC

Technical Specifications – Graphics

Intel® UHD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features Supports HDCP 2.2 Supports BT2020 and HDR playback (7th Gen processors only)
VGA (optional)	VGA ouput
USB-C® DP Alt Mode (optional)	DisplayPort over the optional USB-C® module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
34" UHD Supported Resolutions and Refresh Rates. Other resolutions may also work.	640x480 60 Hz640x480 67Hz 640x480 72Hz 640x480 75Hz 720x400 70Hz 800x600 60Hz 800x600 75Hz 1024x768 60Hz 1024x768 75Hz 1280x960 60Hz 1280x720 60Hz 1280x1024 60Hz 1280x1024 75Hz 1440x900 60Hz 1440x900 75Hz 1680x1050 60Hz 1920x1080 60Hz 3440x1440 60Hz (Native Resolution) 3440x1440 30Hz
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

Technical Specifications – Graphics

NVIDIA® GeForce® RTX 2060 Super 8GB Graphics Card

Engine Clock	1650 MHz
Memory Clock	7000 MHz
Memory Size(width)	8 GB(256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	7680x4320@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DVI+HDMI+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<175W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX 550X 4 GB FH PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD® Radeon™ RX 580 8GB GDDR5 Graphics Card

Engine Clock	1266 MHz
Memory Clock	4000 MHz
Memory Size(width)	8 GB (256-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI + DPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<150W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

Technical Specifications – Graphics

NVIDIA® GeForce® RTX 2080 Super 8GB GDDR6

Engine Clock	1815 MHz
Memory Clock	7750 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DPx3 + HDMI + Virtual Link
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<285W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6

Engine Clock	1620 MHz
Memory Clock	7000 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DPx2 + HDMI + DVI+Virtual Link
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<210W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® Quadro P620 2GB Graphics Card

Engine Clock	1354 MHz
Memory Clock	2500 MHz
Memory Size(width)	2GB (128-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx4
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<40W
PCB form-factor with bracket	LP PCB with LP bracket

Technical Specifications – Graphics

NVIDIA® Quadro P400 2GB Graphics Card

Engine Clock	1252 MHz
Memory Clock	2000 MHz
Memory Size(width)	2GB (64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<30W
PCB form-factor with bracket	LP PCB with LP bracket

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

HP EliteDesk 800 G6 Small Form Factor Business PC

Technical Specifications – Graphics

Intel® HD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA (optional)	VGA Output
USB-C® DP Alt Mode (optional)	DisplayPort over the optional USB-C® module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

Technical Specifications – Graphics

AMD® Radeon™ RX550 4 GB PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD Radeon™ 520 1GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB (32-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	2048x1536@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

HP EliteOne 800 G6 23.8-in All-in-One

Intel® UHD Graphics (integrated)

VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)
HDMI-in	Support HDMI-In
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

Technical Specifications – Graphics

AMD® R19M

Architecture	Discrete GPU AMD® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of ~~5~~ 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	3GByte, 128bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenCL 2.0 OpenGL 4.5 AMD® Unified Video Decoder (UVD)
Max. Resolution (DP)	4096 x 2160@60Hz

Nvidia ® N18E-G2R

Architecture	Discrete GPU NVidia® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	8GByte, 128bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenCL 2.0 OpenGL 4.5
Max. Resolution (DP)	4096 x 2160@60Hz

STORAGE

500 GB 7200RPM 3.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	1.028 in/26.11 mm
Width (nominal)	Media diameter: 3.5 in/88.9 mm Physical size: 4 in/102 mm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (Max.)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA HDD

Capacity	2 TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity	500 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity	500 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to 3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	2 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 3500MB/s
Maximum Sequential Write	Up to 3000MB/s
Logical Blocks	3,907,029,168
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 1450MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications – Storage

512 GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2400MB/s
Maximum Sequential Write	Up to 1300MB/s
Logical Blocks	1,000,215,215
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	Up to 0.31 lb (140g) without bezel
Read Speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X
Access time (typical reads, including settling)	Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Technical Specifications – Storage

HP 9.5mm Slim DVD Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)
Write Speeds	DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X
Read Speeds	DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.29 lb (132 g)
Write Speeds	BD-R SL/DL Up to 6X BD-R TL/QL Up to 4X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-RW Up to 6X DVD+R Up to 8X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X
Read Speeds	BD-ROM Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

Technical Specifications – Storage

	BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R Up to 8X DVD+RW Up to 8X BDMV (AACS Compliant Disc) Up to 6x/2x (Read/Play) DVD-RAM Up to 5x DVD-Video (CSS Compliant Disc) Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x CD-DA (DAE) Up to 24X/10X (Read/Play)
Access time (typical reads, including settling)	Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical), CD-ROM: 165 ms (typical) Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical), CD-ROM: 340 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical, 2000 mA maximum
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

NETWORKING AND COMMUNICATIONS

Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) 4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126) 5. Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) IEEE 802.3i 10BASE-T IEEE 802.3u 100BASE-TX IEEE 802.3ab 1000BAE-T IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection

Technical Specifications – Networking and Communications

IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i219LM 10/100/1000 Integrated NIC	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection

Technical Specifications – Networking and Communications

IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i210 10/100/1000 NIC	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection

Technical Specifications – Networking and Communications

IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax • 2.402 - 2.482 GHz 802.11a/n/ac/ax • 4.9 - 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz • 5.825 - 5.850 GHz
Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[3]	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum

Technical Specifications – Networking and Communications

	• 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby: 10mW • Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity[3]	• 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum • 802.11ax, MCS11(HT40): -59dBm maximum • 802.11ax, MCS11(VHT160): -58.5dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber - Radio OFF; LED White - Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.	

Technical Specifications – Networking and Communications

Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Technical Specifications – Networking and Communications

Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[3]	IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum 802.11n HT40(5GHz) : +14.5dBm minimum 802.11ac VHT80(5GHz) : +11.5dBm minimum 802.11ac VHT160(5GHz) : +11.5dBm minimum 802.11ax HT40(2.4GHz) : +10dBm minimum 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[3]	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%

Technical Specifications – Networking and Communications

Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber - Radio OFF; LED Off - Radio ON	

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + BT5	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d

	IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n • 2.402 - 2.482 GHz 802.11a/n/ac • 4.9 - 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz • 5.825 - 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[3]	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum
Power Consumption	Transmit mode :2.0 W Receive mode :1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode :50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[3]	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum

Technical Specifications – Networking and Communications

Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber - Radio OFF; LED OFF - Radio ON	

HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP)

	Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

I/O DEVICES

HP USB Premium Keyboard		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54 lb. (698g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft® PC 99 - 2001	Functionally compliant
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft. (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP	
Warranty Card	Product Notice	

Technical Specifications – Input/Output Devices

HP USB Premium Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)	
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122°F (10° to 50° C)
	Non-operating temperature	-22° to 140°F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2 g peak acceleration
	Non-operating vibration	4 g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	12mA
Mechanical	Connector	USB 2.0
	Type	3D mouse (3 keys and wheel)
	Resolution	800, 1200, 1600 DPI
	Sensor	Pixart PAN3606DL
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2
	Cable length	6 ft. (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC

HP USB Mouse		
Dimensions (H x L x W)	37mm x 115mm x 62.9mm	
Weight	90 +10g/- 5 g	
Color	Black	
Connector	USB	
Mechanical	Resolution	800 DPI sensitivity
	Buttons	Two primary buttons and clickable scroll wheel

HP Wired Desktop 320M Mouse		
Dimensions (H x L x W)	35.5mm x 103.8mm x 63.4mm	
Weight	75.8 +/- 10 g	
Color	Black	
Connector	USB	
Cable Length	1800mm	
Sustainability	Low halogen PCBA	
Mechanical	**Resolution**	1000 DPI sensitivity
	Buttons	Two primary buttons and clickable scroll wheel

Technical Specifications – Input/Output Devices

HP Wired Desktop 320K Keyboard	
Dimensions (H x L x W)	16.7mm x 426.2mm x 110.9mm
Weight	413 +/- 30 g
Color	Black
Connector	USB
Cable Length	1800mm
Keys	104, 105, 107, 109
Operating Voltage	5V
Power Consumption	50mA - 100mA
Switch Life	10M
Switch Type	Plunger
Operating Temperature	10°C to 50°C
Non- Operating Temperature	30°C to 65°C
Operating Humidity	10% to 90%
Non- Operating Humidity	0% to 90%
Sustainability	Greater than 50% post-consumer recycled plastic content and low halogen PCBA

AUDIO/MULTIMEDIA

HP EliteDesk 800 G6 Tower Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteDesk 800 G6 Small Form Factor Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteDesk 800 G6 Desktop Mini Business PC

Technical Specifications – Audio/Multimeda

Type	Integrated
HD Stereo Codec	Realtek ALC3205-CG
Audio I/O Ports	combo audio jack with CTIA and OMTP headset support
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteOne 800 G6 24 & 27 All-in-One

Bang & Olufsen Audio

Type	Integrated
HD Stereo Codec	Realtek ALC3274
Audio I/O Ports	Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port Side headphone connector supports a headphone connections Rear line out connector All ports are 3.5mm and support stereo
Internal Speaker Amplifier	5W per channel class D stereo amplifier for the internal speakers only
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speakers.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes - Stereo

Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone
Optional integrated 5 MP Full HD RGB webcam & microphone; maximum resolution of 2624 x 1976
Optional integrated 5 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 2624 x 1976

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch
Fingerprint matching: Performed on device
Anti-Spoofing: Yes
Windows Hello Support: Yes
Encryption: On sensor
FIPS Compliant: No

POWER

HP EliteDesk 800 G6 Tower Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 SFF Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (35W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (65W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (95W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteOne 800 G6 24 & 27 All-in-One

Technical Specifications – Power

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~45°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	N/A	N/A
80 PLUS Platinum	N/A	350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	550W active PFC / 80 PLUS Platinum 350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	210W active PFC / 80 PLUS Platinum 280W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current				
Rated Input Current with Energy Efficient* Power Supply	65W?1.6A 90W?1.2A 150W?2.2A	260W Platinum?3.1A 350W Platinum?4A	260W Platinum?3.1A 350W Platinum?4A 550W Platinum?6.6A	210W ?2.8A 280W?3.2A
DC Output	+19.5V	+12V	+12V	+12V

Technical Specifications – Power

	DM	SFF	TWR	AiO
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Power Adapter	External power supply	Internal power supply	Internal power supply	Internal power supply
Dimensions	65W: 113.5mm x 55mm x 30mm 90W: 132mm x 57mm x 30mm 150W: 160mm x 80mm x 40mm	165mm x 95mm x 73mm	165mm x 95mm x 73mm	110x110x26mm
Total Cord Length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions:
Load Requirements: 50% and 100%
Input Voltage: 230Vac/50Hz.
For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Technical Specifications – Power

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated Load	-	85%	88%	90%	92%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated Load	70%	82%	85%	87%	89%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ

Technical Specifications – Weights and Dimensions

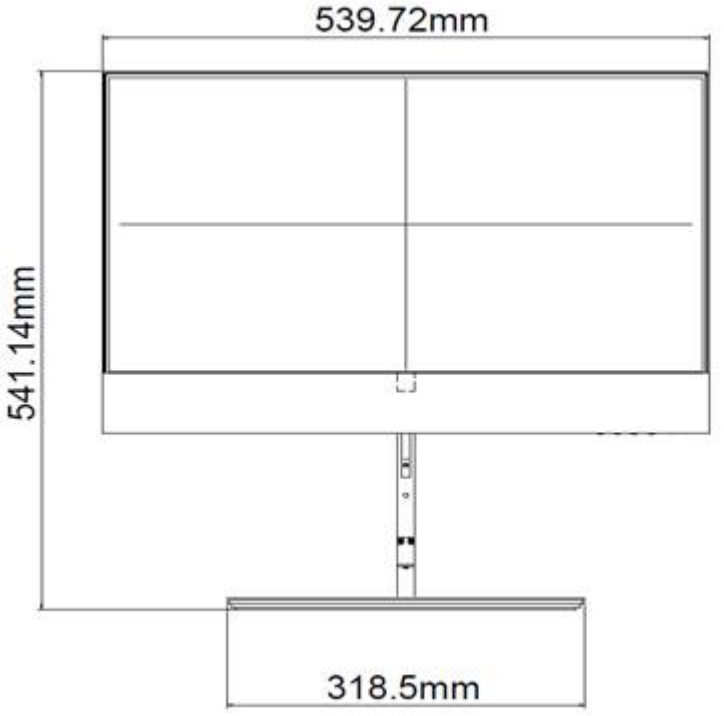
WEIGHTS & DIMENSIONS

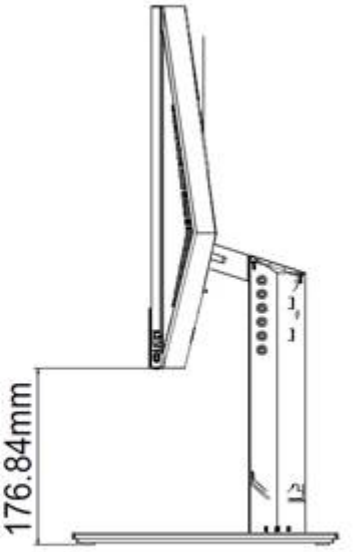
	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34 mm	13.3 x 12.13 x 3.94 in 338 x 308 x 100 mm	14.57 x 12.13 x 6.61 in 370 x 308 x 168 mm	See table below.
System Volume	63.4 cu in 1.05L	63.4 cu in 10.4 L	987.4 cu in 15.89 L	See table below.
System Weight	3.13 lb 1.42 kg	13.5 lb 6.13 kg	21.74 lb 9.86 kg	See table below.
Max Supported Weight (desktop orientation)	0	77 lb 35 kg	77 lb 35 kg	See table below.
Stand Dimensions	160 x 117 x 18.5 mm	151.8 x 200 x 37.2mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 5.2 x 9.3 in 498 x132 x 235 mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm	11.77 x 18.82 x 20.35 in 299 x 478 x 517 mm	See table below.
Shipping Weight	2.95 kg 6.49 lb	9 kg 19.82 lb	11.34 kg 24.98 lb	See table below.
Multipack Packaging (10 units)	20.28 x16.54 x 25 in 515 x 420 x 636 mm			
Palletization Profile	10-units per layer 10 layers max 100 units per pallet 46.3 x 39.2 x 57.7 in, 1175 x 996 x 2125 mm (include pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	8 units per layer 4 layers ax 32 units per pallet 1200 x 1000 x 2203 mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm

STANDS AND DIMENSIONS

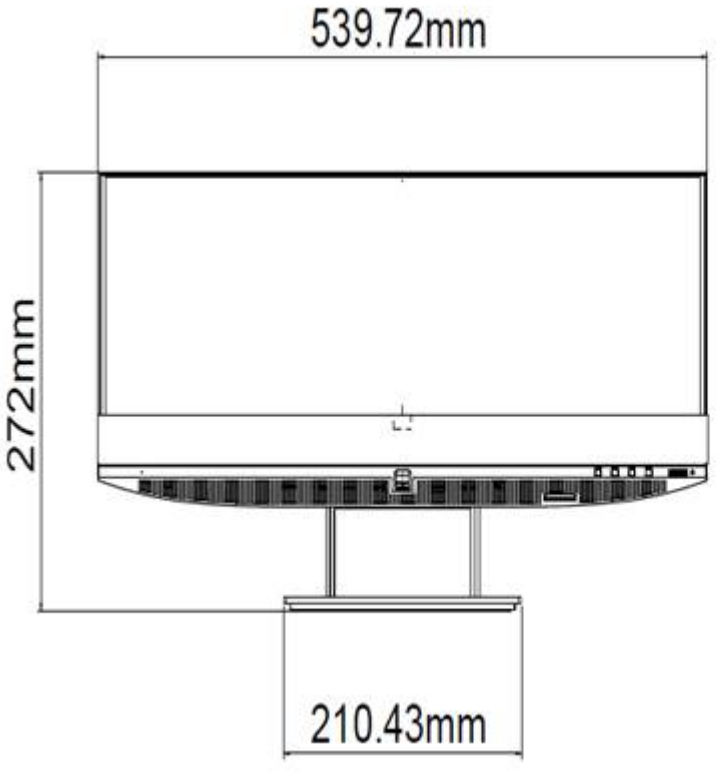
HP EliteOne G6 AIO Adjustable Height Stand - 23.8"?

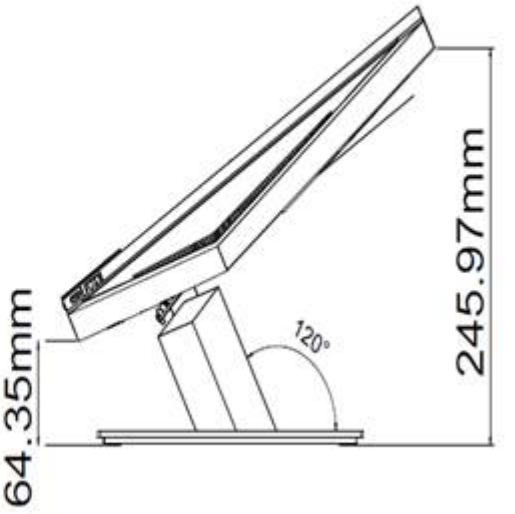
Technical Specifications – Weights and Dimensions





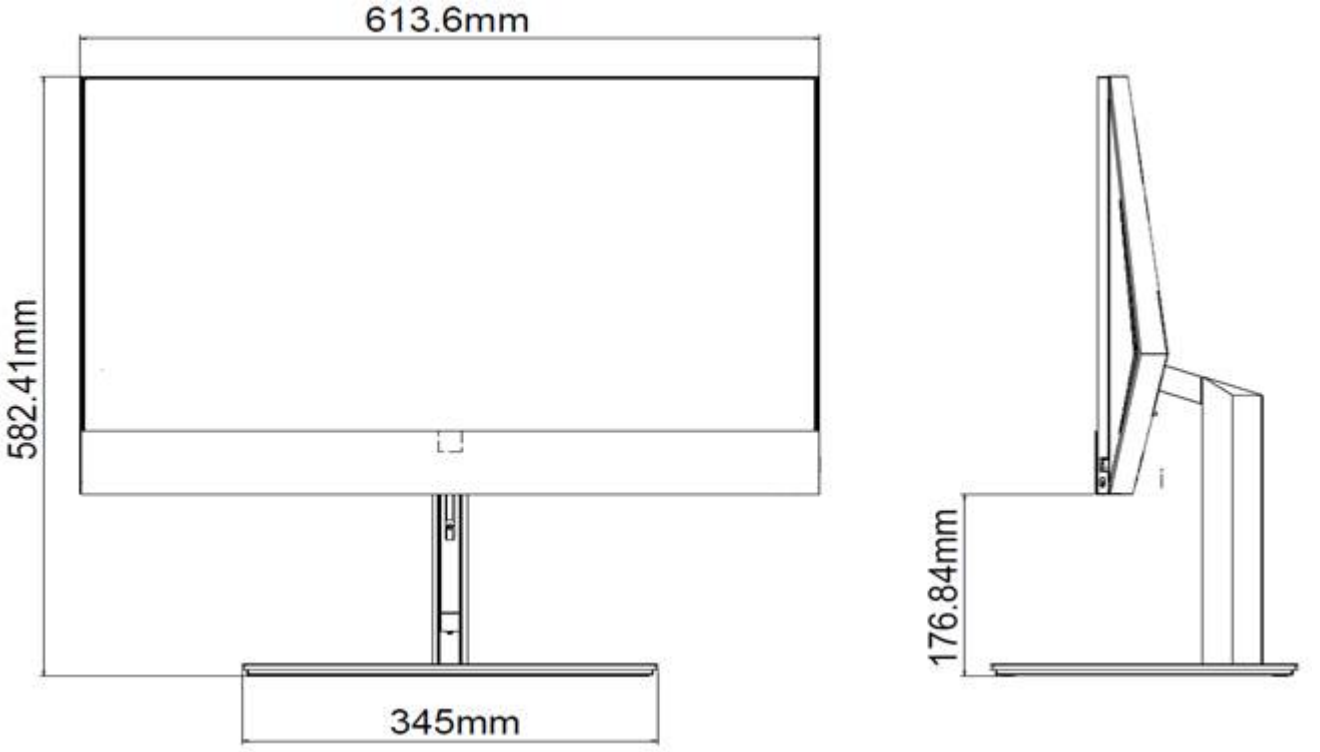
HP EliteOne G6 AIO Recline Stand - 23.8"?





Technical Specifications – Weights and Dimensions

HP EliteOne G6 AIO Adjustable Height Stand - 27"?



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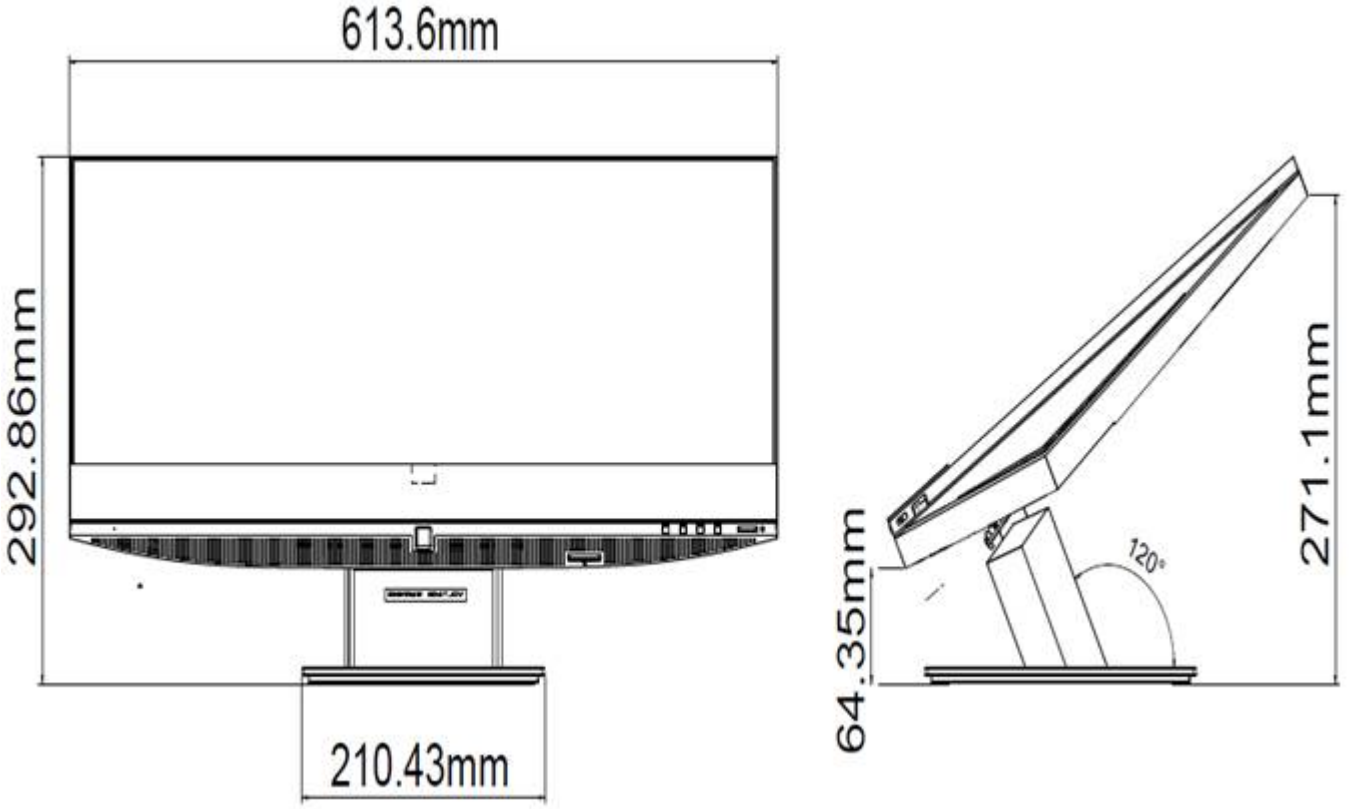
HP EliteOne G6 AIO Recline Stand - 27"?



Technical Specifications – Weights and Dimensions

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot

Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight with Touch Panel - 23.8"?

Product Weight Unboxed	Without Stand 15.12 lbs. 6.86 kg	Adjustable Height Stand 20.46 lbs. 9.28 kg	Recline Stand 18.83 lbs. 8.54 Kg
Shipping Weight Boxed	Without Stand 19.51 lbs. 8.85 kg	Adjustable Height Stand 24.85 lbs. 11.27 kg	Recline Stand 23.08 lbs. 10.47 kg
Shipping Weight Pallet (30 units)	Without Stand 623.7 lbs. 283.5 kg	Adjustable Height Stand 783.4 lbs. 356.1 kg	Recline Stand 730.62 lbs. 332.1 kg

Weight without Touch Panel - 23.8"?

Product Weight Unboxed	Without Stand 17.50 lbs. 7.94 kg	Adjustable Height Stand 22.84 lbs. 10.36 kg	Recline Stand 21.21 lbs. 9.62 Kg
Shipping Weight Boxed	Without Stand 21.89 lbs. 9.93 kg	Adjustable Height Stand 27.23 lbs. 12.35kg	Recline Stand 25.46 lbs. 11.55 kg
Shipping Weight Pallet (30 units)	Without Stand 694.98 lbs. 315.9 kg	Adjustable Height Stand 854.7lbs. 388.5kg	Recline Stand 801.9lbs. 364.5 kg

Dimensions (W x D x H) - 23.8"?

Product Dimensions (Non-touch)	Without Stand 539.72 x 364.3 x 57.3 mm	Adjustable Height Stand (-5 ~ 20) degrees 539.72 x 541.14 x 236.98 mm	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 209.35 mm
Product Dimensions (Sure View/ In-cell Touch)	Without Stand 539.72 x 364.3 x 59.3 mm	Adjustable Height Stand (-5 ~ 20) degrees 539.72 x 541.14 x 236.98 mm	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 211.35 mm

Shipping Dimensions - 23.8"?

Technical Specifications – Weights and Dimensions

Shipping Dimensions Boxed	Without Stand 628 x 186 x 635 mm	Adjustable HeightStand 628 x 186 x 635 mm	Recline Stand 628 x 186 x 635 mm
Shipping Dimensions Pallet Pallet (30 units)	Without Stand 1180 x 874 x 2060 mm	Adjustable Height 1180 x 874 x 2060 mm	Recline Stand 1180 x 874 x 2060 mm

Weight with Touch Panel - 27"?

Product Weight Unboxed	Without Stand 19.56 lbs. 8.87 kg	Adjustable Height Stand 25.40 lbs. 11.52 kg	Recline Stand 23.26 lbs. 10.55 Kg
Shipping Weight Boxed	Without Stand 25.46 lbs. 11.55 kg	Adjustable Height Stand 31.31 lbs. 14.2 kg	Recline Stand 29.17 lbs. 13.23 kg
Shipping Weight Pallet (18 units)	Without Stand 496.98 lbs. 225.9 kg	Adjustable Height Stand 601.92 lbs. 273.6 kg	Recline Stand 563.5 lbs. 256.14 kg

Weight without Touch Panel - 27"?

Product Weight Unboxed	Without Stand 17.79 lbs. 8.07 kg	Adjustable Height Stand 23.63 lbs. 10.72 kg	Recline Stand 21.50 lbs. 9.75 Kg
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Stand 27.40 lbs. 12.43 kg
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg

Dimensions (W x D x H) - 27"?

Product Dimensions (FHD)	Without Stand 613.6 x 405.57 x 58.7 mm	Adjustable Height Stand (-5 ~ 20) degrees 613.6 x 582.41 x 254.98 mm	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 210.68 mm
Product Dimensions (QHD)	Without Stand 613.6 x 405.57 x 59.07 mm	Adjustable Height Stand (-5 ~ 20) degrees 613.6 x 582.41 x 254.98 mm	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 211.05 mm

Shipping Dimensions - 27"?

Technical Specifications – Weights and Dimensions

Shipping Dimensions Boxed	Without Stand 742 x 237 x 640 mm	Adjustable Height Stand 742 x 237 x 640 mm	Recline Stand 742 x 237 x 640 mm
Shipping Dimensions Pallet Pallet (18 units)	Without Stand 1180 x 958 x 2076 mm	Adjustable Height 1180 x 958 x 2076 mm	Recline Stand 1180 x 958 x 2076 mm

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
    - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
    - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
    - 2 red + 4 white BIOS recovery is in progress
    - 3 red + 2 white Memory could not be initialized
    - 3 red + 3 white Graphics adaptor could not be found
    - 3 red + 4 white Power supply failure / not connected
    - 3 red + 5 white Processor not installed
    - 3 red + 6 white Current processor does not support an enabled feature
    - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
    - 4 red + 3 white System internal temperature has exceeded its threshold
    - 5 red + 2 white System controller firmware is not valid
    - 5 red + 3 white System controller detected BIOS is not executing
    - 5 red + 4 white BIOS could not complete initialization / PCA failure
    - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
  - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only. SFF/DM requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy a boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only) A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures we predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

AFTER MARKET OPTIONS

Graphics Solutions	DM	SFF	TWR	AiO	Part Number
AMD® Radeon™ RX 550X 4GB Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	X		5JW82AA
AMD® Radeon™ R7 430 2GB DP+VGA Card		X	X		5JW81AA

Desktop Mini Accessories	DM	SFF	MT	AiO	Part Number
HP Desktop Mini Port Cover v3	X (95W and discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	X (95W and discrete GPU skus not supported)				13L70AA
HP Desktop Mini 65W Power Supply Kit	X				L2X04AA
HP Desktop Mini 90W Power Supply Kit	X				L4R65AA
HP Desktop Mini LockBox V2	X (95W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	X (Either one)				K9Q83AA
HP Desktop Mini I/O Expansion Module					K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v3	X (95W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	X (95W and discrete GPU skus not supported)				13L68AA
HP B250 PC Mounting Bracket	X				8RA46AA
HP B300 PC Mounting Bracket	X				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	X (95W and discrete GPU skus not supported)				7DB37AA
HP B500 PC Mounting Bracket	X				2DW52AA
HP Desktop Mini Vertical Chassis Stand	X				G1K23AA
HP DM Power Supply Holder Kit v2	X (95W and discrete GPU skus not supported)				7DB38AA
HP Quick Release Bracket 2	X			X	6KD15AA
HP Single Monitor Arm	X			X	BT861AA

Technical Specifications – After Market Options

Data Storage Drives	DM	SFF	TWR	AiO	Part Number
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X	X8U75AA
HP 500GB 7200PRM SATA 3.5"? Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 3.5"? Hard Drive		X	X		QK555AA
HP 9.5mm Tower DVD-Writer		X	X		1CA52AA

Input Devices	DM	SFF	TWR	AiO	Part Number
HP Desktop Wired 320K Keyboard	X	X	X	X	9SR37AA
HP Desktop Wired 320M Mouse	X	X	X	X	9VA80AA
HP Desktop Wired 320MK Mouse and Keyboard	X	X	X	X	9SR36AA
HP USB Antimicrobial Business Slim Keyboard and Mouse	X	X	X	X	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	X	X	X	Z9H48AA
HP USB Keyboard	X	X	X	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X	1VD81AA
HP USB Premium Keyboard	X	X	X	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	X	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X	N3R88AA
HP Wireless Premium Keyboard	X	X	X	X	Z9N41AA
HP PS/2 Business Slim Keyboard		X	X		N3R86AA
HP USB Fingerprint Mouse	X	X	X	X	4TS44AA
HP USB Premium Mouse	X	X	X	X	1JR32AA
HP PS/2 Mouse		X	X		QY775AA
HP Wireless Premium Mouse	X	X	X	X	1JR31AA
HP USB 1000dpi Laser Mouse	X	X	X	X	QY778AA
HP USB Optical Mouse	X	X	X	X	QY777AA
HP USB Hardened Mouse[1]	X	X	X	X	P1N77AA

1. Not available in all regions

Technical Specifications – After Market Options

System Memory	DM	SFF	TWR	AiO	Part Number
HP 4GB DDR4-2666 DIMM		X	X		3TK85AA
HP 8GB DDR4-2666 DIMM		X	X		3TK87AA
HP 16GB DDR4-2666 DIMM		X	X		3TK83AA
HP 32GB DDR4-2666 DIMM		X	X		1C918AA
HP 4GB DDR4-2666 SODIMM	X			X	3TK86AA
HP 8GB DDR4-2666 SODIMM	X			X	3TK88AA
HP 16GB DDR4-2666 SODIMM	X			X	3TK84AA
HP 32GB DDR4-2666 SODIMM	X			X	1C919AA
HP 4GB DDR4-3200 UDIMM		X	X		13L78AA
HP 8GB DDR4-3200 UDIMM		X	X		13L76AA
HP 16GB DDR4-3200 UDIMM		X	X		13L74AA
HP 32GB DDR4-3200 UDIMM		X	X		13L72AA
HP 4GB DDR4-3200 SODIMM	X			X	13L79AA
HP 8GB DDR4-3200 SODIMM	X			X	13L77AA
HP 16GB DDR4-3200 SODIMM	X			X	13L75AA
HP 32GB DDR4-3200 SODIMM	X			X	13L73AA

Multimedia Devices	DM	SFF	TWR	AiO	Part Number
HP Business Headset v2	X	X	X	X	T4E61AA
HP S101 Speaker Bar	X	X	X		5UU40AA
HP UC Speaker Phone v2	X	X	X		4VW02AA

Security Devices	DM	SFF	TWR	AiO	Part Number
HP Business PC Security Lock v3 Kit		X	X		3XJ17AA
HP Dual Head Keyed Cable Lock		X	X		T1A64AA
HP Keyed Cable Lock 10mm	X	X	X	X	T1A62AA
HP Master Keyed Cable Lock 10mm	X	X	X	X	T1A63AA
HP Sure Key Cable lock	X				6UW42AA

Stands and Accessories	DM	SFF	TWR	AiO	Part Number
HP EliteOne 800 G6 23.8"? Height Adjustable Stand				X	13L61AA
HP EliteOne 800 G6 23.8" Recline Stand				X	13L62AA
HP EliteOne 800 G6 27"? Height Adjustable Stand				X	13L63AA
HP EliteOne 800 G6 27"? Recline Stand				X	13L64AA

Technical Specifications – After Market Options

I/O Devices	DM	SFF	TWR	AiO	Part Number
HP DisplayPort Port Flex IO v2	X	X	X		13L54AA
HP HDMI Port Flex IO v2	X	X	X		13L55AA
HP Thunderbolt 3.0	X	X (occupies a PCIe slot)	X (occupies a PCIe slot)		4CX35AA
HP Type-C® USB 3.1 Gen2 Port Flex IO v2	X	X	X		13L59AA
HP Type-C® USB 3.1 Gen2 Port with PD Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)				13L60AA
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	X	X		13L58AA
HP VGA Port Flex IO v2	X	X	X		13L53AA
HP Serial Port Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	X	X		13L56AA
HP Serial Port Flex IO 2 v2	X (Not Available on 95W and discrete GPU SKUs)				13L57AA
HP Internal Serial Port (in rear wall)		X	X		3TK82AA
HP PCIe x1 Parallel Port Card		X	X		N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		X	X		1VD82AA
HP USB to Serial Port Adapter	X	X	X		J7B60AA
HP USB-C to Display Port Adapter	X	X	X		N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)				2MY05AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	DM	SFF	TWR	AiO	Part Number
Intel® Ethernet I210-T1 GbE NIC		X	X		E0X95AA

Intel® Optane Memory	DM	SFF	TWR	AiO	Part Number
Intel® Optane Memory 16GB (Cache)	X	X	X		1WV97AA
512GB Intel® Optane™ Memory H10 with SSD	X	X	X	X	6VF55AA

Change Log

Date	Version History	Action	Description of Change
July 15, 2020	From v1 to v2	Addition	Supported versions section
July 22, 2020	From v2 to v3	Addition	NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6